Abstract of the Disclosure

An integrated circuit that includes a frame carrier interposer and at least one electronic device mounted to the frame carrier interposer. The frame carrier interposer includes a conductive foil that is laminated to only a dry film and electrically connected to the at least one electronic device. A method of fabricating an integrated circuit that includes laminating a conductive foil to only a dry film to form a frame carrier interposer and patterning the conductive foil.



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